



HYPOXY CLEARBOND CLEAR EPOXY ADHESIVE

PRODUCT: H-200 1Lb (454 gms) Pack.

DESCRIPTION: A two-component epoxy formulation highly filled with carefully selected modified curing agents, and special high quality additives to provide maximum strength, durability, and ease of application. Will adhere to vertical surfaces and is formulated for clarity.

It Bonds rigidly to varieties of substrates such as metals, glass, ceramics, concrete, and wood in all combinations. It forms a clear hard rigid bond self leveling liquid in minutes & get functional cure in few hours. The cured deposit is 100% reactive having no solvents. The Low viscosity (Approx 8,000 cps) makes it useful for varieties of industrial adhesive applications.

APPLICATIONS:

HYPOXY CLEARBOND ADHESIVE hardens to a Transparent mass and adheres soundly to all metal & non metal surfaces. A permanent, non-shrinking epoxy based industrial grade adhesive is recommended as Potting compound in Electrical & Electronic Industry.

It is Universally used for repairing and bonding electronic components, ceramics, plastic, wood, concrete and where a clear color is desirable.

It is widely used for the repair of models, toys, lamps, vases, furniture, picture frames and appliances.

HYPOXY CLEARBOND® bonds wood, fiberglass, metals, glass, china, ceramics and most plastics (not polyethylene) and is unaffected by liquids such as water, oil, and gasoline.

The HYPOXY CLEARBOND deposit offers a very high Dielectric strength makes it most suitable adhesive for holding PCB mounted Electronic components against vibrations, Electro magnetic forces.



PHYSICAL PROPERTIES:

Colour :-	Clear
Consistency :-	Liquid
Pot Life 1 lb. @ 24°C (75°F) :-	45 minutes
Mixed Viscosity :-	8,000 cps
Cure Shrinkage :-	0.0005 in/in
Temperature Resistance :-	250°F (121°C)
Hardness (Shore, ASTM D 1706) :-	80D
Compression Strength (ASTM D 695) :-	11,000 psi
Dielectric Strength (ASTM D 149) :-	600 volts/mil

CHEMICAL RESISTANCE:

Hydrochloric Acid 10% :-	Fair
Hydrochloric Acid 50% :-	Fair
Sulfuric Acid 10% :-	Fair
Sulfuric Acid 50% :-	Fair
Water :-	Very Good
Ammonia :-	Very Good
Sodium Hydroxide 10% :-	Very Good
Gasoline, Oil, Kerosene :-	Very Good
Mineral Spirits :-	Very Good
Toluene :-	Good
Methanol :-	Fair



DIRECTIONS:

Surfaces must be clean, dry, and preferably roughened for maximum adhesion.

For 1 lb. kits add all of the resin (Part A) to all of the hardener (Part B) in the hardener can. For smaller portions, dole out 1 part hardener to 1 parts resin by volume.

MIX THOROUGHLY, making certain that all of the hardener comes in contact with all of the resin. While mixing be sure to scrape the sides and bottom of the container. This will ensure proper cure and achieve the stated strengths.

Apply the mixed compound with putty knife, spatula, or similar tool.

CURING TIME:

At 75°F (24°C) a ½" (12.5mm) layer of HY-POXY KLEARBOND putty will be hard in approximately 2 hours. FULL cure times are as follows:

TEMPERATURE	WORKING TIME	FULL CURE TIME
60°F (16°C)	90 Minutes	32 Hours
75°F (24°C)	45 Minutes	16 Hours
90°F (32°C)	25 Minutes	8 Hours

Heat lamp or sunlight will accelerate the cure.

SAFETY :

Before using any product, review the appropriate Material Safety Data Sheet (MSDS). Follow standard confined space entry and work procedures, if appropriate.

NON-WARRANTY:

We can accept no responsibility or liability for lack of results because the storage, handling, and application of the compound is beyond our control.

PL CALL IN YOUR LOCAL AUTHORISED DEALER TO GET FULL ADVANTAGE OF PRODUCT TRAINING AND KNOW HOW TO MAKE MORE USE OF HY POXY PRODUCTS



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